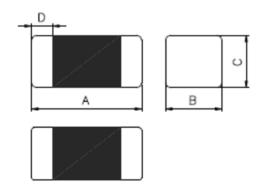


FEATRLRES

- Monolithic inorganic material construction.
- Closed magnetic circuit avoids crosstalk.
- S.M.T. type.
- Suitable for reflow soldering.
- Shapes and dimensions follow E.I.A. spec.
- Available in various sizes.
- Excellent solder ability and heat resistance.
- High reliability.
- 100% Lead(Pb) & Halogen-Free and RoHS compliant.

CONFIGRLRATIONS & DIMENSIONS (unit in mm)



Size	A	В	С	D
FCI2012	2.0+0.2	0.8±0		0.5±0.30
rCI2012	2.0±0.2	1.23±0.2	1.25±0.20	0.5±0.50

ELECTRICAL CHARACTERISTICS

Doub Normhou	Thickness	Indu	ctance(uH)	(Q	Rated	DCR	SRF
Part Number	C size(mm)	Tolerance	Test Frequency	min.	Test	(mA) max.	(Ω) max.	(MHz)
FCI2012F-47N□	0.85±0.20	0.047	60mV / 50M	15	50	300	0.20	320
FCI2012F-68N	0.85 ± 0.20	0.068	60mV / 50M	15	50	300	0.20	280
FCI2012F-82N□	0.85 ± 0.20	0.082	60mV / 50M	15	50	300	0.20	255
FCI2012F-R10□	0.85 ± 0.20	0.10	60mV / 25M	20	25	250	0.30	235
FCI2012F-R12	0.85 ± 0.20	0.12	60mV / 25M	20	25	250	0.30	220
FCI2012F-R15□	0.85 ± 0.20	0.15	60mV / 25M	20	25	250	0.40	200
FCI2012F-R18□	0.85 ± 0.20	0.18	60mV / 25M	20	25	250	0.40	185
FCI2012F-R22	0.85 ± 0.20	0.22	60mV / 25M	20	25	250	0.50	170
FCI2012F-R27□	0.85 ± 0.20	0.27	60mV / 25M	20	25	250	0.50	150
FCI2012F-R33□	0.85 ± 0.20	0.33	60mV / 25M	20	25	250	0.55	145
FCI2012F-R39□	0.85 ± 0.20	0.39	60mV / 25M	25	25	200	0.65	135
FCI2012F-R47□	1.25±0.20	0.47	60mV / 25M	25	25	200	0.65	125
FCI2012F-R56	1.25±0.20	0.56	60mV / 25M	25	25	150	0.75	115



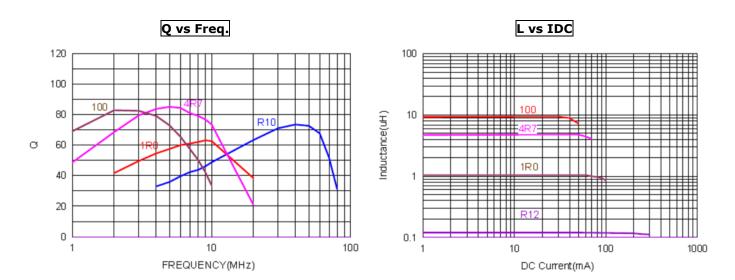
FCI2012F-R68	1.25±0.20	0.68	60mV / 25M	25	25	150	0.80	105
FCI2012F-1R0	0.85 ± 0.20	1.0	60mV / 10M	45	10	50	0.40	75
FCI2012F-1R5	0.85 ± 0.20	1.5	60mV / 10M	45	10	50	0.50	60
FCI2012F-1R8	0.85 ± 0.20	1.8	60mV / 10M	45	10	50	0.60	55
FCI2012F-2R2	0.85 ± 0.20	2.2	60mV / 10M	45	10	30	0.65	50
FCI2012F-2R7	1.25±0.20	2.7	60mV / 10M	45	10	30	0.75	45
FCI2012F-3R3	1.25±0.20	3.3	60mV / 10M	45	10	30	0.80	41
FCI2012F-4R7	1.25±0.20	4.7	60mV / 10M	45	10	30	1.00	35
FCI2012F-100	1.25±0.20	10.0	60mV / 2M	45	2	15	1.15	24

NOTE: \square : TOLERANCE $K=\pm 10\%, L=\pm 15\%, M=\pm 20\%$

■ Rated current: based on temperature rise test

■ In compliance with EIA 595

Q vs Frequency,DC Bias Characteristics(Typical)



Reliability and Test Condition

Item	Performance	Test Condition			
Operating temperature	-40~+125℃ (Including self - temperature rise)				
Storage temperature	110~+40°C,50~60%RH (Product with taping) 240~+125°C (on board)				
Electrical Performance Test					
Inductance		HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.			
DCR	Refer to standard electrical characteristics list.	CH16502,Agilent33420A Micro-Ohm Meter.			
Saturation Current (Isat)	Approximately△L30%	Saturation DC Current (Isat) will cause L0 to drop △L(%)			



Heat Rated Current (Irms)	Approximately △T40°C	Heat Rated Current (Irms) will cause the coil temperature rise $\triangle T(^{\circ}C)$. 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer
Reliability Test	•	
Life Test		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature: 125±2°C (Inductor) Applied current: rated current Duration: 1000±12hrs Measured at room temperature after placing for 24±2 hrs
Load Humidity		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity: 85±2 * R.H, Temperature: 85°C±2°C Duration: 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs
Moisture Resistance	Appearance: No damage. Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles 1. Baked at50°C for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs. 3. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs, keep at 25°C for 2 hrs then keep at -10°C for 3 hrs 4. Keep at 25°C 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1: -40±2°C 30±5min Step2: 25±2°C ≤0.5min Step3: 125±2°C 30±5min Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs
Vibration		Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes Equipment: Vibration checker Total Amplitude:1.52mm±10% Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations).
Bending		Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.
Shock	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Type Peak value (g's) Normal duration (D) (ms) Wave form Velocity change (vi)ft/sec SMD 50 11 Half-sine 11.3 Lead 50 11 Half-sine 11.3
Solder ability	More than 95% of the terminal electrode should be covered with solder.	Preheat: 150°C,60sec Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5°C ∘ Flux for lead free: Rosin. 9.5% ∘ Dip time: 4±1sec ∘ Depth: completely cover the termination
Resistance to Soldering Heat		Depth: completely cover the termination Temperature (°C) Time(s) Temperature ramp/immersion and emersion rate leat cycles lead to the complete ramp and emersion rate lead to the complete rate rate rate rate rate rate rate r
		(solder temp) 10 ±1 25mm/s ±6 mm/s 1



	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value e	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a force(>0805:1kg, <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60+1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.
Terminal Strength		DUT wide thick substrate press tool

Note : When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.